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SEMICONDUCTOR



ESD



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PLED

MBXXXF-MS

Product specification

FEATURES

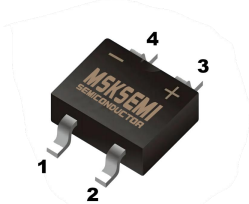
- Reverse Voltage - 40 to 200 V
- Forward Current - 2 A
- High Surge Current Capability
- Designed for Surface Mount Application

MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

Reference News

PACKAGE OUTLINE



MBF

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

MB24F-MS



MB26F-MS



MB28F-MS



MB210F-MS



MB220F-MS



Maximum Ratings and Electrical characteristics

Ratings at 25 ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB24F-MS	MB26F-MS	MB28F-MS	MB210F-MS	MB220F-MS	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	60	80	100	200	V
Maximum RMS voltage	V_{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current at $T_c = 100\text{ }^\circ\text{C}$	$I_{F(AV)}$	2.0					A
Peak Forward Surge Current ,8 .3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50		40			A
Max Instantaneous Forward Voltage at 2 A	V_F	0.55	0.70	0.85			V
Maximum DC Reverse Current at Rated DC Reverse Voltage $T_a = 25\text{ }^\circ\text{C}$ $T_a = 100\text{ }^\circ\text{C}$	I_R	0.5 10			0.3 5		mA
Typical Junction Capacitance ¹⁾	C_j	220	80				pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	75					$^\circ\text{C/W}$
Operating Junction Temperature Range	T_j	-55 ~ +150					$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 ~ +150					$^\circ\text{C}$

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Typical Characteristics

Fig.1 Forward Current Derating Curve

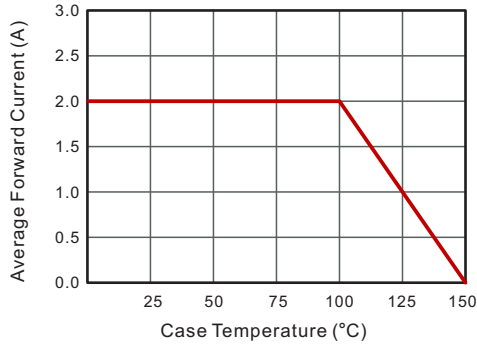


Fig.2 Typical Reverse Characteristics

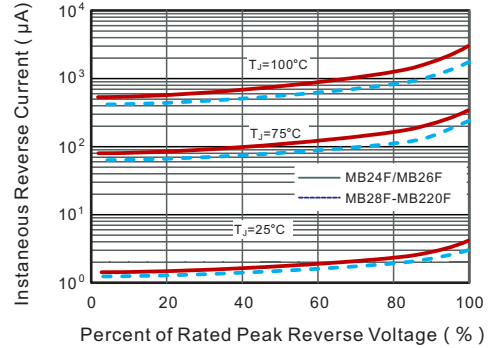


Fig.3 Typical Forward Characteristic

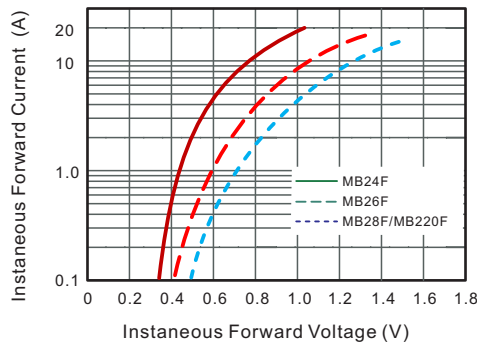


Fig.4 Typical Junction Capacitance

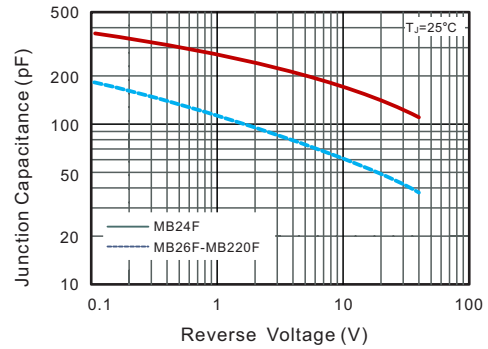


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

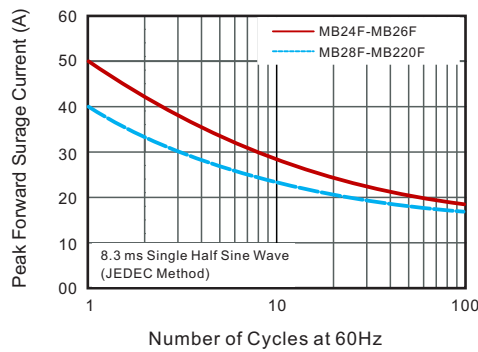
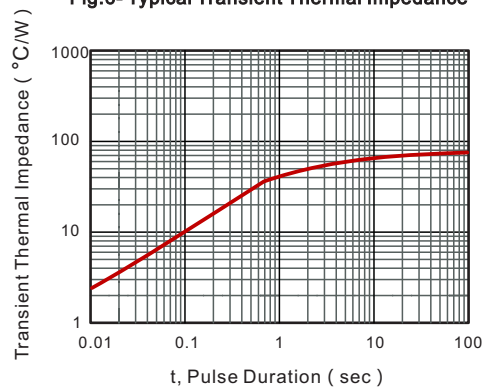
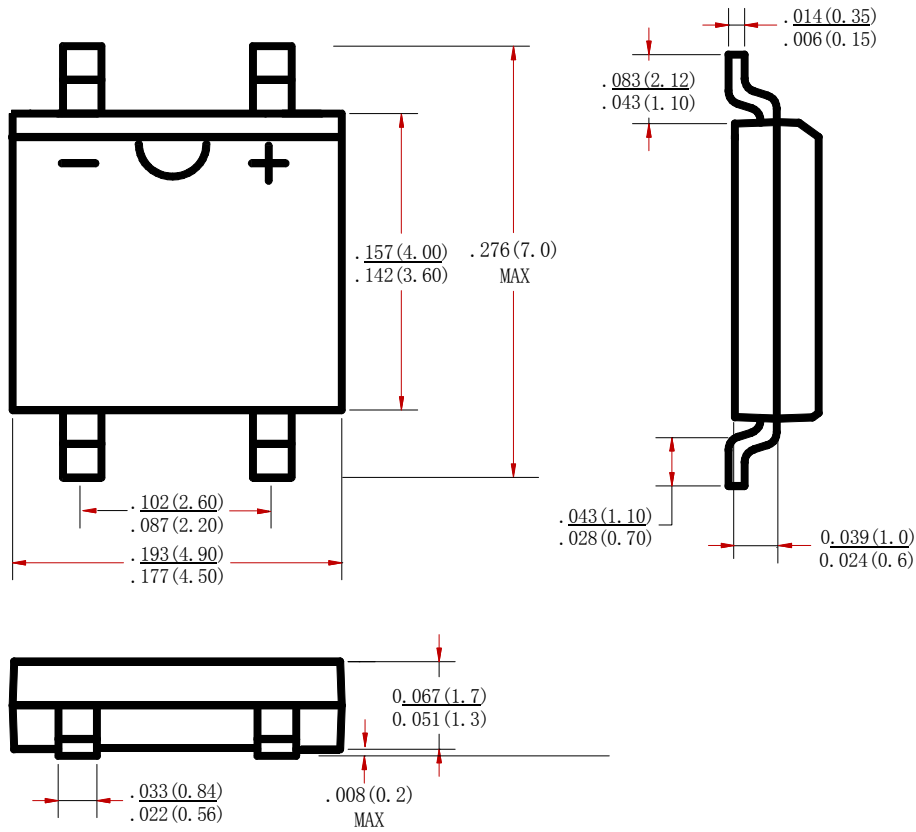


Fig.6- Typical Transient Thermal Impedance

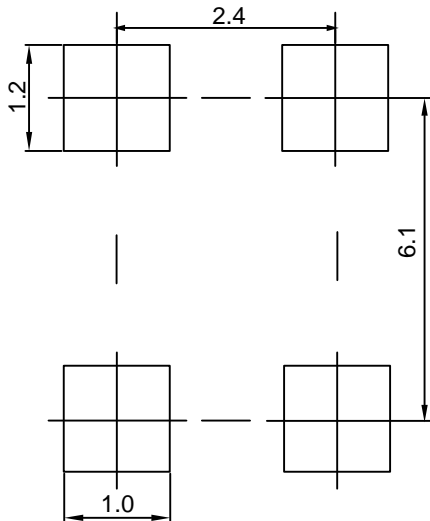


MBF Package Outline Dimensions



Dimensions in inches and (millimeters)

MBF Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MBXXXF-MS	MBF	5000

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